Ultra Series™ Crystal Oscillator (VCXO) Si566 Data Sheet

Ultra Low Jitter Dual Any-Frequency VCXO (100 fs), 0.2 to 3000 MHz

The Si566 Ultra Series™ voltage-controlled crystal oscillator utilizes Silicon Laboratories' advanced 4th generation DSPLL® technology to provide an ultra-low jitter, low phase noise clock at two selectable frequencies. The device is factory-programmed to provide any two selectable frequencies from 0.2 to 3000 MHz with <1 ppb resolution and maintains exceptionally low jitter for both integer and fractional frequencies across its operating range. On-chip power supply filtering provides industry-leading power supply noise rejection, simplifying the task of generating low jitter clocks in noisy systems that use switched-mode power supplies. Offered in industry-standard 3.2x5 mm and 5x7 mm footprints, the Si566 has a dramatically simplified supply chain that enables Silicon Labs to ship custom frequency samples 1-2 weeks after receipt of order. Unlike a traditional XO, where a different crystal is required for each output frequency, the Si566 uses one simple crystal and a DSPLL IC-based approach to provide the desired output frequencies. The Si566 is factory-configurable for a wide variety of user specifications, including frequency, output format, and OE pin location/polarity. Specific configurations are factory-programmed at time of shipment, eliminating the long lead times associated with custom oscillators.

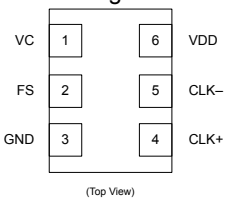
KEY FEATURES

- Available with any two selectable frequencies from 200 kHz to 3000 MHz
- Ultra low jitter: 100 fs RMS typical (12 kHz – 20 MHz)
- Excellent PSRR and supply noise immunity: –80 dBc Typ
- 3.3 V, 2.5 V and 1.8 V V_{DD} supply operation from the same part number
- LVPECL, LVDS, CML, HCSL, CMOS, and Dual CMOS output options
- 3.2x5, 5x7 mm package footprints
- Samples available with 1-2 week lead times

APPLICATIONS

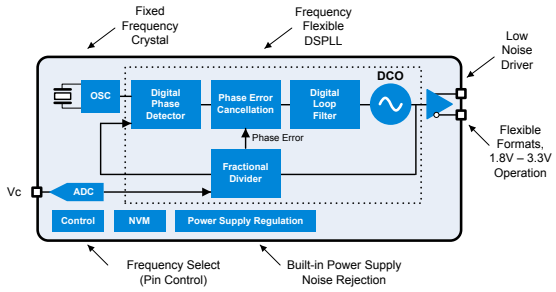
- 100G/200G/400G OTN, coherent optics
- 10G/25G/40G/100G Ethernet
- 56G/112G PAM4 clocking
- 3G-SDI/12G-SDI/24G-SDI broadcast video
- Servers, switches, storage, NICs, search acceleration
- Test and measurement
- FPGA/ASIC clocking

Pin Assignments



(Top View)

Pin #	Descriptions
1	VC = Voltage Control Pin
2	FS = Frequency Select
3	GND = Ground
4	CLK+ = Clock output
5	CLK- = Complementary clock output. Not used for CMOS.
6	VDD = Power supply



1. Ordering Guide

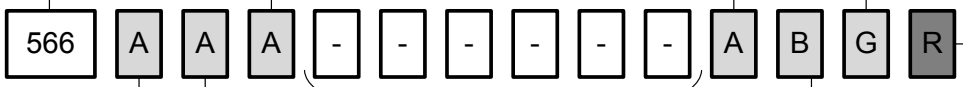
The Si566 VCXO supports a variety of options including frequency, output format, and OE pin location/polarity, as shown in the chart below. Specific device configurations are programmed into the part at time of shipment, and samples are available in 1-2 weeks. Silicon Laboratories provides an online part number configuration utility to simplify this process. Refer to www.silabs.com/oscillators to access this tool and for further ordering instructions.

VCXO Series	Description
566	Dual Frequency VCXO

Code	VC Pin	FS Pin
A	Pin 1	Pin 2

	Package
A	5x7 mm
B	3.2x5 mm

	Temperature Grade
G	-40 to 85 °C



Signal Format	VDD Range	Order Option
LVPECL	2.5, 3.3 V	A
LVDS	1.8, 2.5, 3.3 V	B
CMOS	1.8, 2.5, 3.3 V	C
CML	1.8, 2.5, 3.3 V	D
HCSL	1.8, 2.5, 3.3 V	E
Dual CMOS (In-Phase)	1.8, 2.5, 3.3 V	F
Dual CMOS (Complementary)	1.8, 2.5, 3.3 V	G
Custom[1]	1.8, 2.5, 3.3 V	X

	Temperature Stability = ± 20 ppm			
	Vc Tuning Slope Kv [ppm/V]	Min APR [± ppm] at VDD [3]		
		3.3V	2.5V	1.8V
A	60	20	--	--
B	75	40	20	--
C	105	70	40	20
D	150	115	75	45
E	180	145	100	65
F	225	190	135	85

Frequency Code [2]	Description
xxxxxx	Two unique frequencies can be specified within the supported range of the selected signal format. Either frequency can be assigned to FS=0 or FS=1. A six digit numeric code will be assigned for the specific combination of frequencies.

Code	Reel
R	Tape and Reel
<Blank>	Coil Tape

Notes:

1. Contact Silicon Labs for non-standard configurations.
2. Create custom part numbers at www.silabs.com/oscillators.
3. Min Absolute Pull Range (APR) includes temp stability, initial accuracy, load pulling, VDD variation, and 20 year aging at 70 °C.
   a. For best jitter and phase noise performance, always choose the smallest Kv that meets the application's minimum APR requirements. Unlike SAW-based solutions which require higher Kv values to account for their higher temperature dependence, the Si56x series provides lower Kv options to minimize noise coupling and jitter in real-world PLL designs.
   b. APR is the ability of a VCXO to track a signal over the product lifetime. A VCXO with an APR of ±20 ppm is able to lock to a clock with a ±20 ppm stability over 20 years over all operating conditions.
   c. APR (±) = (0.5 x VDD x tuning slope) - (initial accuracy + temp stability + load pulling + VDD variation + aging).
   d. Minimum APR values noted above include absolute worst case values for all parameters.
   e. See application note, "AN266: VCXO Tuning Slope (Kv), Stability, and Absolute Pull Range (APR)" for more information.

1.1 Technical Support

Frequently Asked Questions (FAQ)	www.silabs.com/Si566-FAQ
Oscillator Phase Noise Lookup Utility	www.silabs.com/oscillator-phase-noise-lookup
Quality and Reliability	www.silabs.com/quality
Development Kits	www.silabs.com/oscillator-tools

2. Electrical Specifications

Table 2.1. Electrical Specifications

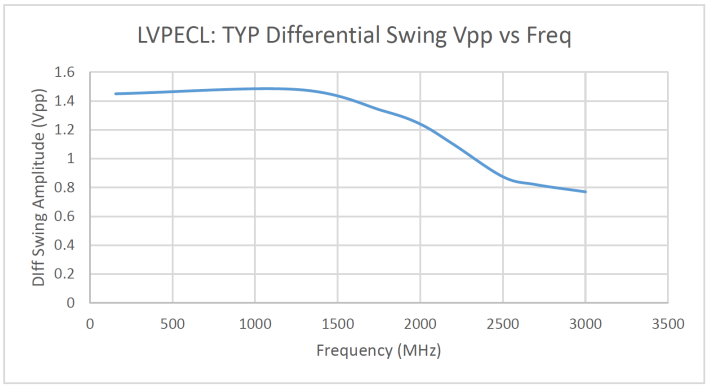
V_{DD} = 1.8 V, 2.5 or 3.3 V ± 5%, T_A = –40 to 85 ºC

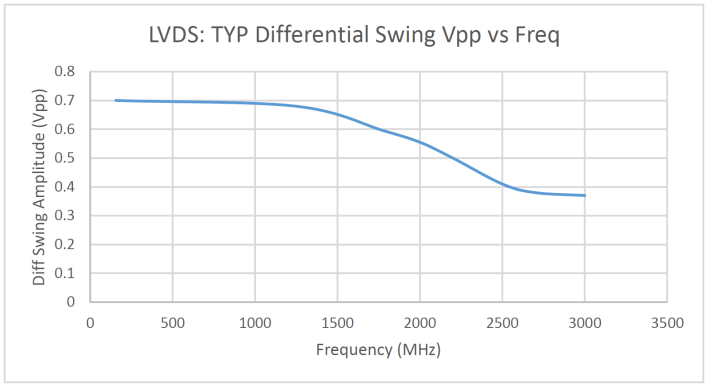
Parameter	Symbol	Test Condition/Comment	Min	Typ	Max	Unit
Temperature Range	T_A		–40	—	85	ºC
Frequency Range	F_{CLK}	LVPECL, LVDS, CML	0.2	—	3000	MHz
		HCSL	0.2	—	400	MHz
		CMOS, Dual CMOS	0.2	—	250	MHz
Supply Voltage	V_{DD}	3.3 V	3.135	3.3	3.465	V
		2.5 V	2.375	2.5	2.625	V
		1.8 V	1.71	1.8	1.89	V
Supply Current	I_{DD}	LVPECL (output enabled)	—	120	170	mA
		LVDS/CML (output enabled)	—	100	167	mA
		HCSL (output enabled)	—	95	140	mA
		CMOS (output enabled)	—	95	145	mA
		Dual CMOS (output enabled)	—	105	155	mA
		Tristate Hi-Z (output disabled)	—	83	—	mA
Temperature Stability[1]		-40 to 85 °C	–20	—	20	ppm
Rise/Fall Time (20% to 80% V_{PP})	T_R/T_F	LVPECL/LVDS/CML	—	—	350	ps
		CMOS / Dual CMOS (C_L = 5 pF)	—	0.5	1.5	ns
		HCSL, F_{CLK} >50 MHz	—	—	550	ps
Duty Cycle	D_C	All formats	45	—	55	%
Frequency Select (FS)[2]	V_{IH}		0.7 × V_{DD}	—	—	V
	V_{IL}		—	—	0.3 × V_{DD}	V
	T_{FS}	Settling Time after FS Change	—	—	10	ms
Powerup Time	t_{OSC}	Time from 0.9 × V_{DD} until output frequency (F_{CLK}) within spec	—	—	10	ms
LVPECL Output Option[3]	V_{OC}	Mid-level	V_{DD} – 1.42	—	V_{DD} – 1.25	V
	V_O	Swing (diff, $F_{CLK} \leq$ 1.5 GHz)	1.1	—	1.9	V_{PP}
		Swing (diff, F_{CLK} > 1.5 GHz)[6]	0.55	—	1.7	V_{PP}
LVDS Output Option[4]	V_{OC}	Mid-level (2.5 V, 3.3 V VDD)	1.125	1.20	1.275	V
		Mid-level (1.8 V VDD)	0.8	0.9	1.0	V
	V_O	Swing (diff, $F_{CLK} \leq$ 1.5 GHz)	0.5	0.7	0.9	V_{PP}
		Swing (diff, F_{CLK} > 1.5 GHz) [6]	0.25	0.5	0.8	V_{PP}

Parameter	Symbol	Test Condition/Comment	Min	Typ	Max	Unit
HCSL Output Option[5]	V_{OH}	Output voltage high	660	800	850	mV
	V_{OL}	Output voltage low	–150	0	150	mV
	V_C	Crossing voltage	250	410	550	mV
CML Output Option (AC-Coupled)	V_O	Swing (diff, $F_{CLK} \leq 1.5$ GHz)	0.6	0.8	1.0	V_{PP}
		Swing (diff, $F_{CLK} > 1.5$ GHz)[6]	0.3	0.55	0.9	V_{PP}
CMOS Output Option	V_{OH}	I_{OH} = 8/6/4 mA for 3.3/2.5/1.8 V VDD	0.85 × V_{DD}	—	—	V
	V_{OL}	I_{OL} = 8/6/4 mA for 3.3/2.5/1.8 V VDD	—	—	0.15 × V_{DD}	V

Notes:

1. Min APR includes temperature stability, initial accuracy, load pulling, VDD variation, and aging for 20 yrs at 70 ºC.
2. FS pin includes a 50 kΩ pull-up to VDD.
3. R_{term} = 50 Ω to V_{DD} – 2.0 V (see Figure 4.1).
4. R_{term} = 100 Ω (differential) (see Figure 4.2).
5. R_{term} = 50 Ω to GND (see Figure 4.2).
6. Refer to the figure below for Typical Clock Output Swing Amplitudes vs Frequency.





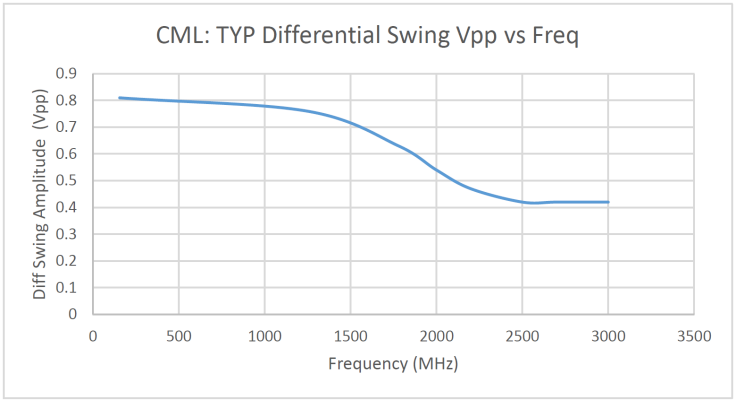


Figure 2.1. Typical Clock Output Swing Amplitudes vs. Frequency

Table 2.2. V_C Control Voltage Input

V_{DD} = 1.8, 2.5 or 3.3 V ± 5%, T_A = –40 to 85 ºC

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Control Voltage Range	V_C		0.1 x VDD	VDD/2	0.9 x VDD	V
Control Voltage Tuning Slope (Vc = 10% VDD to 90% VDD)	Kv	Positive slope, ordering option	60, 75, 105, 150, 180, 225			ppm/V
Kv Variation	Kv_var		—	—	±10	%
Control Voltage Linearity	LVC	Best Straight Line fit	–1.5	±0.5	+1.5	%
Modulation Bandwidth	BW		—	10	—	kHz
Vc Input Impedance	ZVC		500	—	—	kΩ

Table 2.3. Clock Output Phase Jitter and PSRR

V_{DD} = 1.8 V, 2.5 or 3.3 V ± 5%, T_A = –40 to 85 ºC

Parameter	Symbol	Test Condition/Comment	Min	Typ	Max	Unit
Phase Jitter (RMS, 12 kHz - 20 MHz)[1] All Differential Formats, F_{CLK} ≥ 200 MHz	ϕJ	Kv = 60 ppm/V	—	100	150	fs
		Kv = 75 ppm/V	—	103	—	fs
		Kv = 105 ppm/V	—	110	—	fs
		Kv = 150 ppm/V	—	123	—	fs
		Kv = 180 ppm/V	—	132	—	fs
		Kv = 225 ppm/V	—	150	—	fs
Phase Jitter (RMS, 12 kHz - 20 MHz) [1] All Diff Formats, 100 MHz ≤ F_{CLK} < 200 MHz	ϕJ	Kv = 60 ppm/V	—	115	170	fs
		Kv = 75 ppm/V	—	118	—	fs
		Kv = 105 ppm/V	—	125	—	fs
		Kv = 150 ppm/V	—	138	—	fs
		Kv = 180 ppm/V	—	147	—	fs
		Kv = 225 ppm/V	—	165	—	fs
Phase Jitter (RMS, 12 kHz - 20 MHz)[1] LVDS, F_{CLK} = 156.25 MHz	ϕJ	Kv = 60 ppm/V	—	110	130	fs
		Kv = 75 ppm/V	—	113	—	fs
		Kv = 105 ppm/V	—	120	—	fs
		Kv = 150 ppm/V	—	133	—	fs
		Kv = 180 ppm/V	—	142	—	fs
		Kv = 225 ppm/V	—	160	—	fs
Phase Jitter (RMS, 12 kHz - 20 MHz)[1] CMOS / Dual CMOS Formats	ϕJ	10 MHz ≤ F_{CLK} < 250 MHz	—	200	—	fs

Parameter	Symbol	Test Condition/Comment	Min	Typ	Max	Unit
Spurs Induced by External Power Supply Noise, 50 mVpp Ripple. LVDS 156.25 MHz Output	PSRR	100 kHz sine wave		-83		dBc
		200 kHz sine wave		-83		
		500 kHz sine wave		-82		
		1 MHz sine wave		-85		

Note:
1. Jitter inclusive of any spurs.

Table 2.4. 3.2 x 5 mm Clock Output Phase Noise (Typical)

Offset Frequency (f)	156.25 MHz LVDS	200 MHz LVDS	644.53125 MHz LVDS	Unit
100 Hz	–73	–71	–60	
1 kHz	–102	–102	–93	
10 kHz	–130	–128	–118	
100 kHz	–141	–139	–129	dBc/Hz
1 MHz	–150	–148	–138	
10 MHz	–159	–160	–153	
20 MHz	–160	–162	–154	
Offset Frequency (f)	**156.25 MHz LVPECL**	**200 MHz LVPECL**	**644.53125 MHz LVPECL**	**Unit**
100 Hz	–72	–71	–60	
1 kHz	–103	–101	–92	
10 kHz	–130	–127	–117	
100 kHz	–142	–139	–129	dBc/Hz
1 MHz	–150	–148	–138	
10 MHz	–160	–162	–154	
20 MHz	–161	–162	–156	

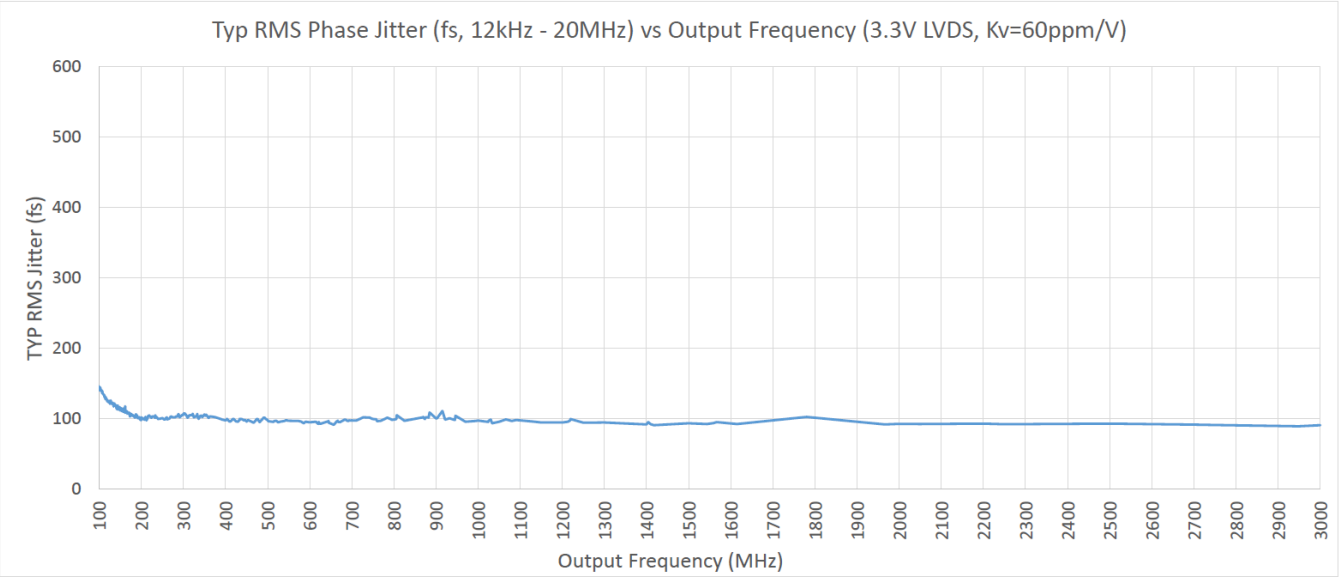


Figure 2.2. Phase Jitter vs. Output Frequency

Phase jitter measured with Agilent E5052 using a differential-to-single ended converter (balun or buffer). Measurements collected for >700 commonly used frequencies. Phase noise plots for specific frequencies are available using our free, online Oscillator Phase Noise Lookup Tool at www.silabs.com/oscillators.

Table 2.5. Environmental Compliance and Package Information

Parameter	Test Condition
Mechanical Shock	MIL-STD-883, Method 2002
Mechanical Vibration	MIL-STD-883, Method 2007
Solderability	MIL-STD-883, Method 2003
Gross and Fine Leak	MIL-STD-883, Method 1014
Resistance to Solder Heat	MIL-STD-883, Method 2036
Moisture Sensitivity Level (MSL)	1
Contact Pads	Gold over Nickel

Note:

1. For additional product information not listed in the data sheet (e.g. RoHS Certifications, MDDS data, qualification data, REACH Declarations, ECCN codes, etc.), refer to our "Corporate Request For Information" portal found here: www.silabs.com/support/quality/Pages/RoHSInformation.aspx.

Table 2.6. Thermal Conditions

Package	Parameter	Symbol	Test Condition	Value	Unit
3.2 × 5 mm 6-pin CLCC	Thermal Resistance Junction to Ambient	Θ_{JA}	Still Air, 85 °C	80.3	°C/W
	Thermal Resistance Junction to Board	Θ_{JB}	Still Air, 85 °C	50.8	°C/W
	Max Junction Temperature	T_J	Still Air, 85 °C	125	°C
5 × 7 mm 6-pin CLCC	Thermal Resistance Junction to Ambient	Θ_{JA}	Still Air, 85 °C	68.4	°C/W
	Thermal Resistance Junction to Board	Θ_{JB}	Still Air, 85 °C	52.9	°C/W
	Max Junction Temperature	T_J	Still Air, 85 °C	125	°C

Table 2.7. Absolute Maximum Ratings[1]

Parameter	Symbol	Rating	Unit
Maximum Operating Temp.	T_{AMAX}	95	°C
Storage Temperature	T_S	–55 to 125	°C
Supply Voltage	V_{DD}	–0.5 to 3.8	°C
Input Voltage	V_{IN}	–0.5 to V_{DD} + 0.3	V
ESD HBM (JESD22-A114)	HBM	2.0	kV
Solder Temperature[2]	T_{PEAK}	260	°C
Solder Time at T_{PEAK}[2]	T_P	20–40	sec

Notes:

1. Stresses beyond those listed in this table may cause permanent damage to the device. Functional operation specification compliance is not implied at these conditions. Exposure to maximum rating conditions for extended periods may affect device reliability.
2. The device is compliant with JEDEC J-STD-020.

3. Dual CMOS Buffer

Dual CMOS output format ordering options support either complementary or in-phase signals for two identical frequency outputs. This feature enables replacement of multiple VCXOs with a single Si566 device.

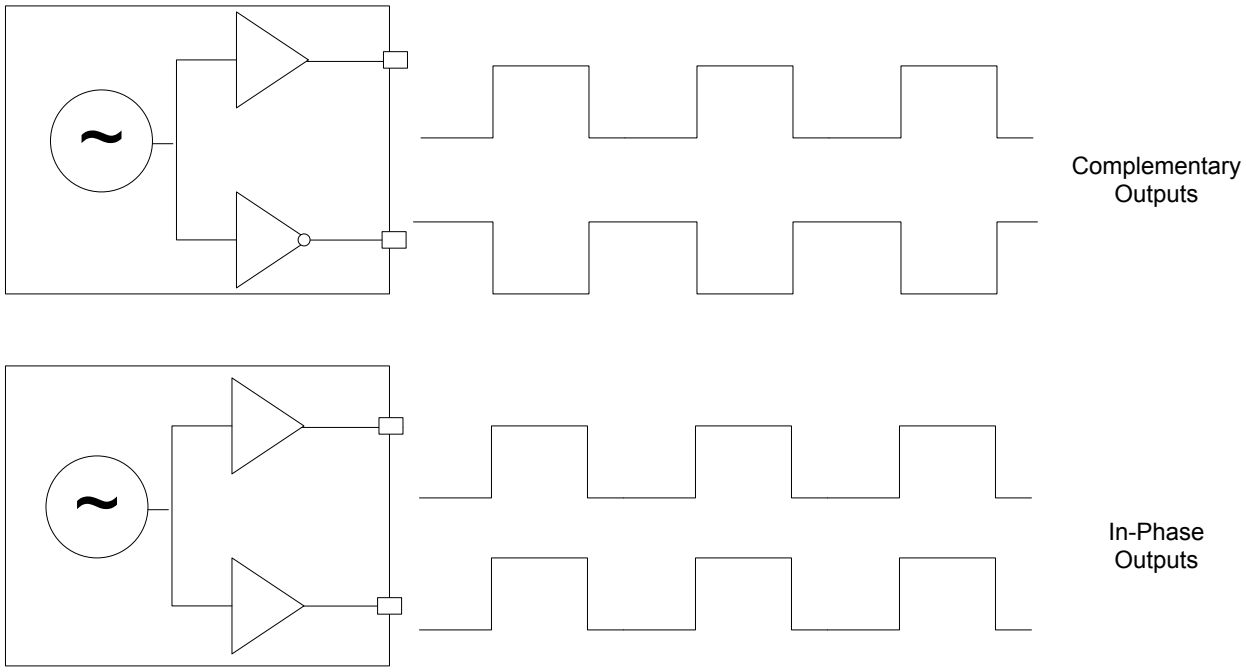


Figure 3.1. Integrated 1:2 CMOS Buffer Supports Complementary or In-Phase Outputs

4. Recommended Output Terminations

The output drivers support both AC-coupled and DC-coupled terminations as shown in figures below.

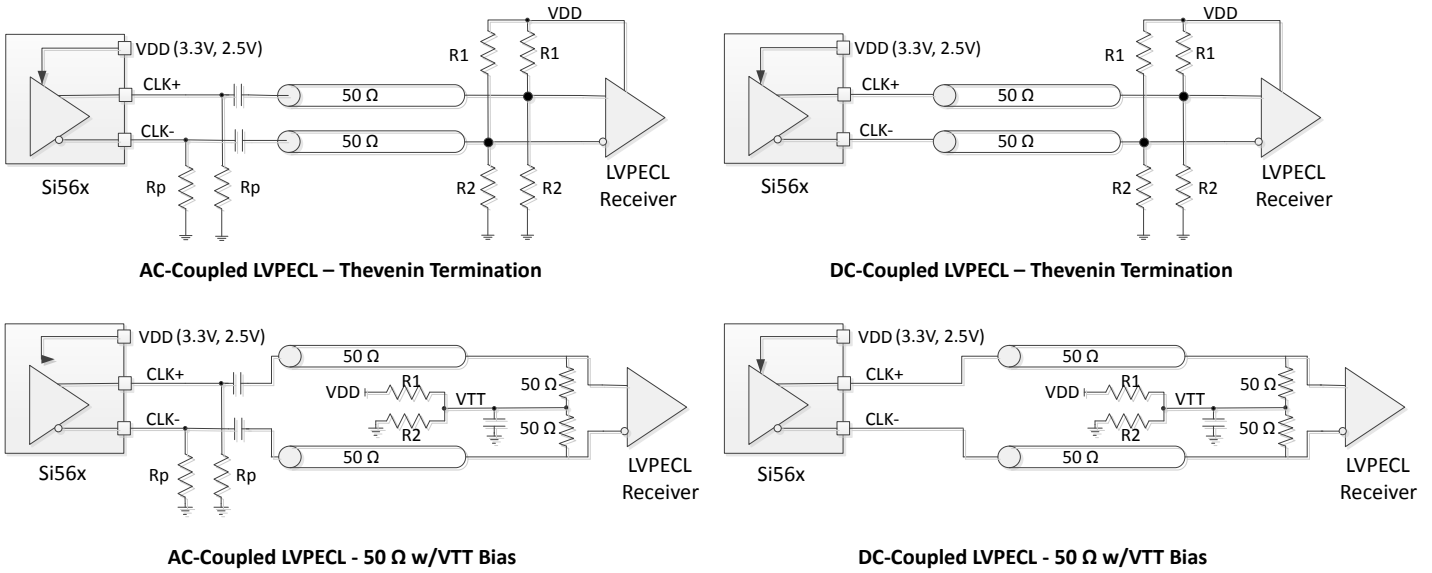


Figure 4.1. LVPECL Output Terminations

AC-Coupled LVPECL Termination Resistor Values			
VDD	R1	R2	Rp
3.3 V	127 Ω	82.5 Ω	130 Ω
2.5 V	250 Ω	62.5 Ω	90 Ω

DC-Coupled LVPECL Termination Resistor Values		
VDD	R1	R2
3.3 V	127 Ω	82.5 Ω
2.5 V	250 Ω	62.5 Ω

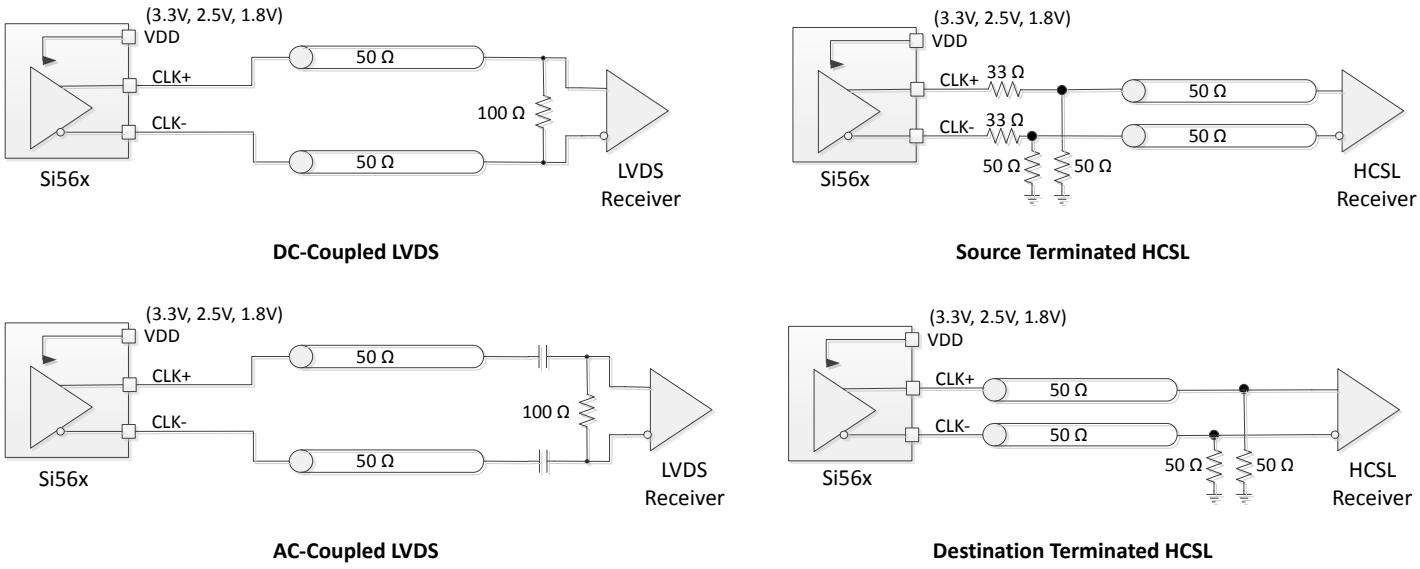


Figure 4.2. LVDS and HCSL Output Terminations

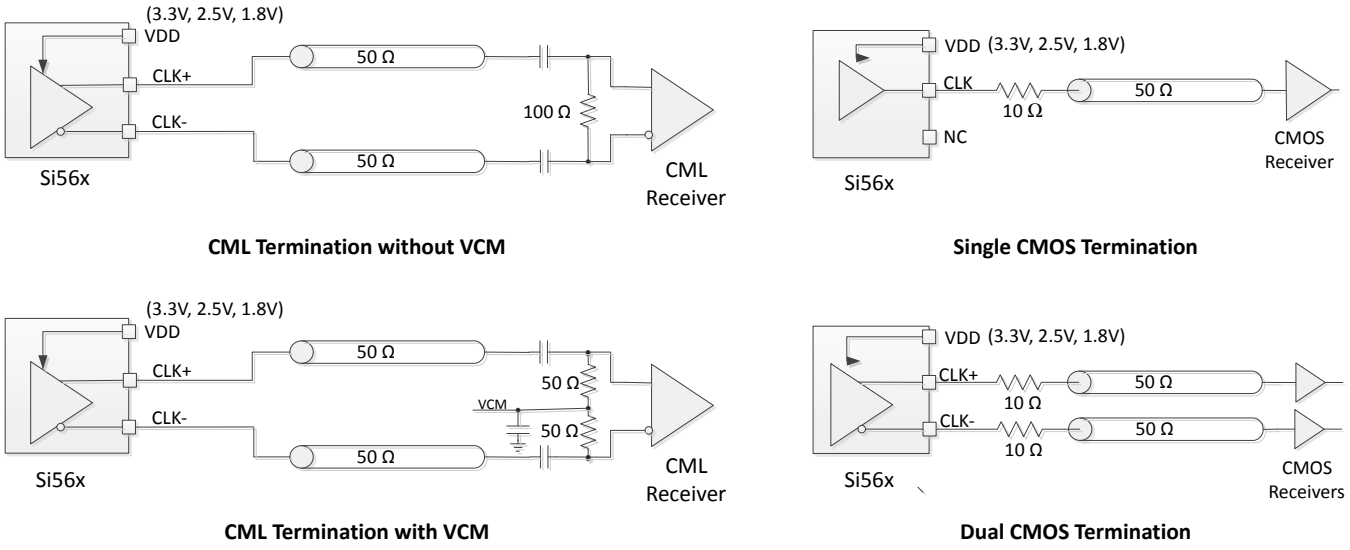


Figure 4.3. CML and CMOS Output Terminations

5. Package Outline

5.1 Package Outline (5×7 mm)

The figure below illustrates the package details for the 5×7 mm Si566. The table below lists the values for the dimensions shown in the illustration.

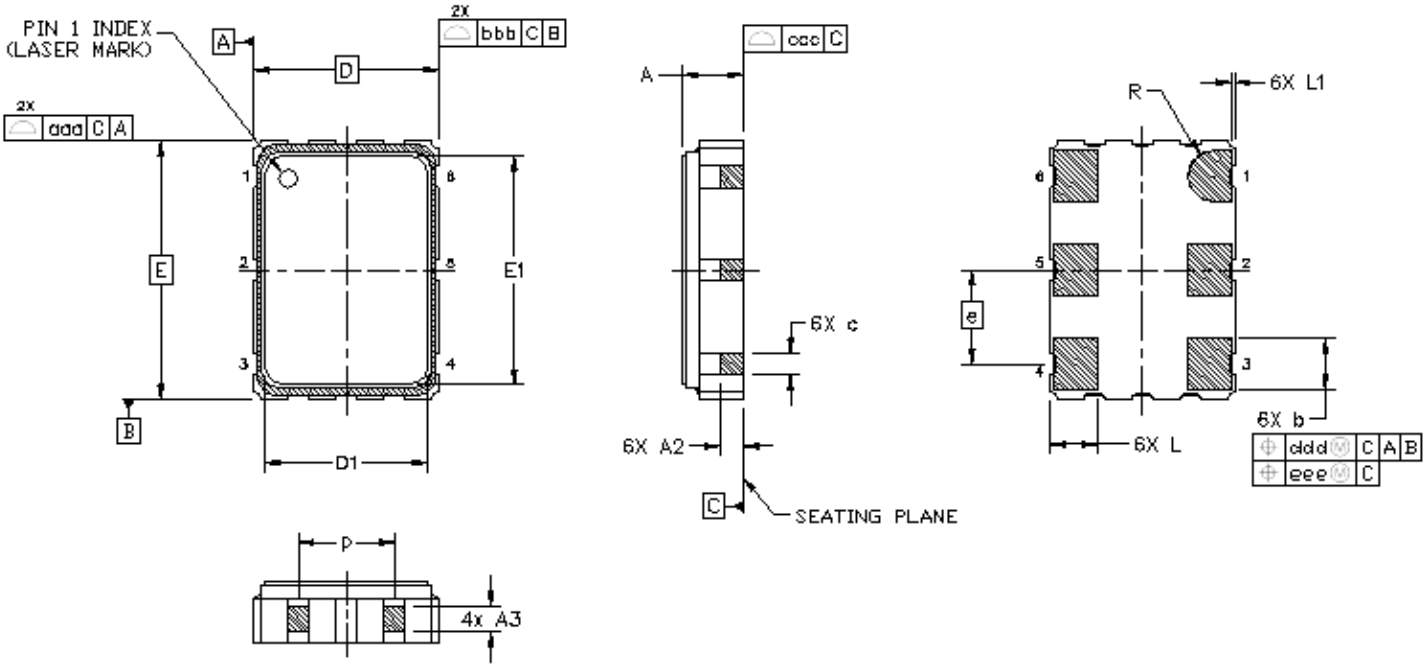


Figure 5.1. Si566 (5×7 mm) Outline Diagram

Table 5.1. Package Diagram Dimensions (mm)

Dimension	Min	Nom	Max		Dimension	Min	Nom	Max
A	1.13	1.28	1.43		L	1.17	1.27	1.37
A2	0.50	0.55	0.60		L1	0.05	0.10	0.15
A3	0.50	0.55	0.60		p	1.70	—	1.90
b	1.30	1.40	1.50		R	0.70 REF		
c	0.50	0.60	0.70		aaa	0.15		
D	5.00 BSC				bbb	0.15		
D1	4.30	4.40	4.50		ccc	0.08		
e	2.54 BSC				ddd	0.10		
E	7.00 BSC				eee	0.05		
E1	6.10	6.20	6.30					

Notes:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.

5.2 Package Outline (3.2×5 mm)

The figure below illustrates the package details for the 3.2×5 mm Si566. The table below lists the values for the dimensions shown in the illustration.

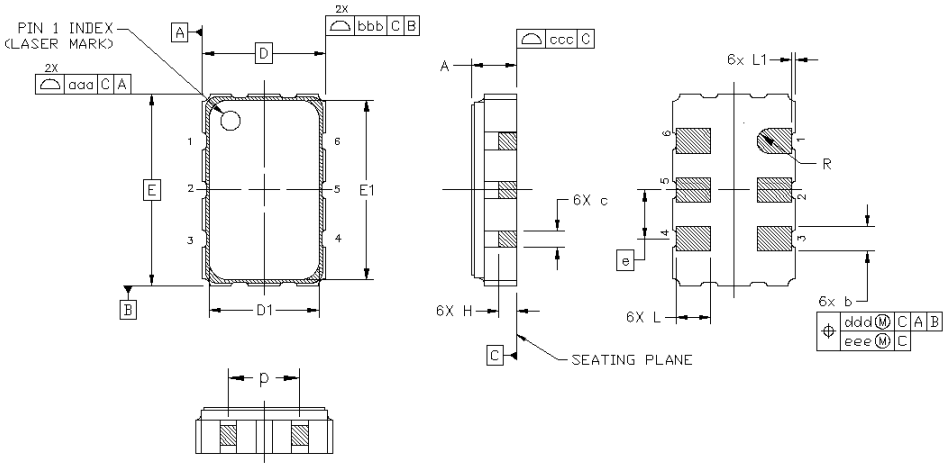


Figure 5.2. Si566 (3.2×5 mm) Outline Diagram

Table 5.2. Package Diagram Dimensions (mm)

Dimension	Min	Nom	Max
A	1.06	1.17	1.33
b	0.54	0.64	0.74
c	0.35	0.45	0.55
D		3.20 BSC	
D1	2.55	2.60	2.65
e		1.27 BSC	
E		5.00 BSC	
E1	4.35	4.40	4.45
H	0.45	0.55	0.65
L	0.80	0.90	1.00
L1	0.05	0.10	0.15
p	1.36	1.46	1.56
R		0.32 REF	
aaa		0.15	
bbb		0.15	
ccc		0.08	
ddd		0.10	
eee		0.05	

Notes:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.

6. PCB Land Pattern

6.1 PCB Land Pattern (5×7 mm)

The figure below illustrates the 5×7 mm PCB land pattern for the Si566. The table below lists the values for the dimensions shown in the illustration.

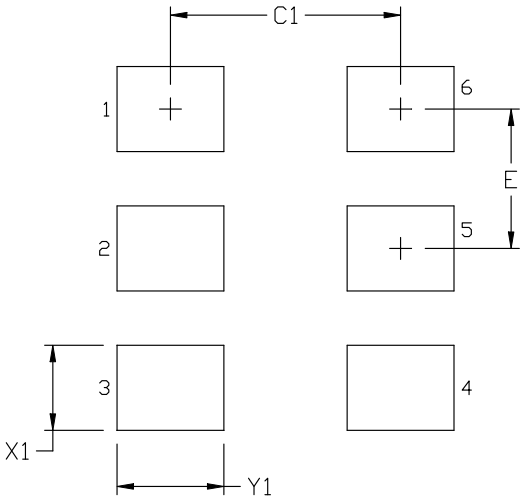


Figure 6.1. Si566 (5×7 mm) PCB Land Pattern

Table 6.1. PCB Land Pattern Dimensions (mm)

Dimension	(mm)
C1	4.20
E	2.54
X1	1.55
Y1	1.95

Notes:

General

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
3. This Land Pattern Design is based on the IPC-7351 guidelines.
4. All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

Solder Mask Design

1. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.

Stencil Design

1. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
2. The stencil thickness should be 0.125 mm (5 mils).
3. The ratio of stencil aperture to land pad size should be 1:1.

Card Assembly

1. A No-Clean, Type-3 solder paste is recommended.
2. The recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.

6.2 PCB Land Pattern (3.2×5 mm)

The figure below illustrates the 3.2×5.0 mm PCB land pattern for the Si566. The table below lists the values for the dimensions shown in the illustration.

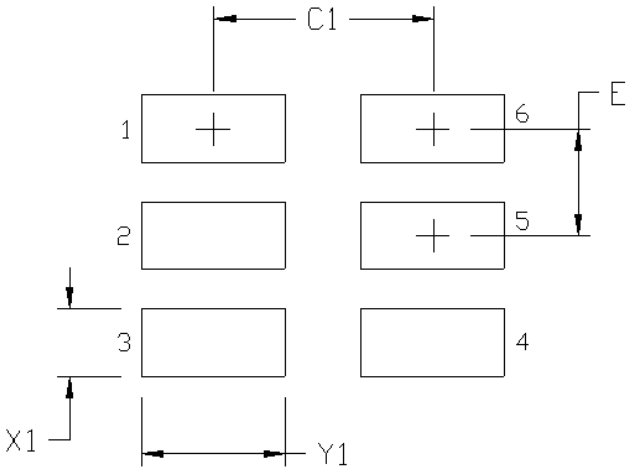


Figure 6.2. Si566 (3.2×5 mm) PCB Land Pattern

Table 6.2. PCB Land Pattern Dimensions (mm)

Dimension	(mm)
C1	2.60
E	1.27
X1	0.80
Y1	1.70

Notes:

General

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
3. This Land Pattern Design is based on the IPC-7351 guidelines.
4. All dimensions shown are at Maximum Material Condition (MMC). Least Material Condition (LMC) is calculated based on a Fabrication Allowance of 0.05 mm.

Solder Mask Design

1. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.

Stencil Design

1. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
2. The stencil thickness should be 0.125 mm (5 mils).
3. The ratio of stencil aperture to land pad size should be 1:1.

Card Assembly

1. A No-Clean, Type-3 solder paste is recommended.
2. The recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.

7. Top Marking

The figure below illustrates the mark specification for the Si566. The table below lists the line information.

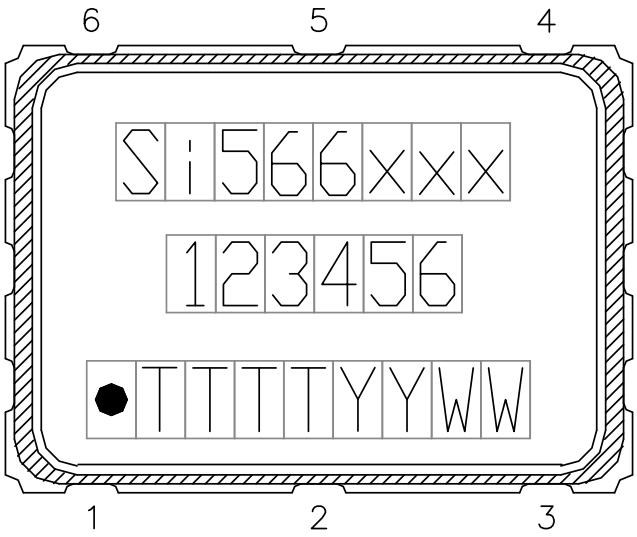


Figure 7.1. Mark Specification

Table 7.1. Si566 Top Mark Description

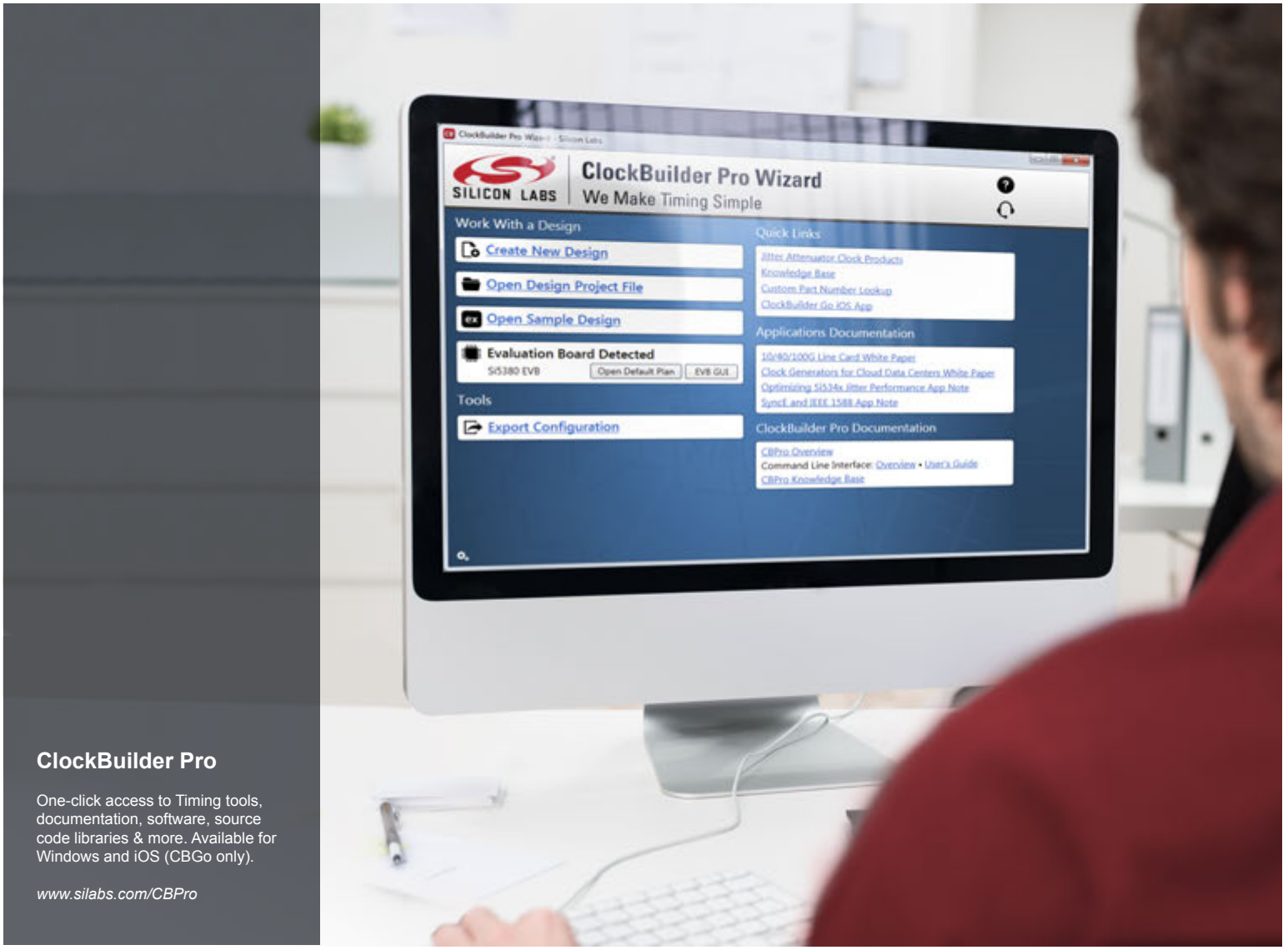
Line	Position	Description
1	1–8	"Si566", xxx = Ordering Option 1, Option 2, Option 3 (e.g. Si566AAA)
2	1–6	Frequency Code (6-digit custom code as described in the Ordering Guide)
3	**Trace Code**	
	Position 1	Pin 1 orientation mark (dot)
	Position 2	Product Revision (B)
	Position 3–5	Tiny Trace Code (3 alphanumeric characters per assembly release instructions)
	Position 6–7	Year (last two digits of the year), to be assigned by assembly site (ex: 2017 = 17)
	Position 8–9	Calendar Work Week number (1–53), to be assigned by assembly site

8. Revision History

Revision 1.0

June, 2018

- Initial draft



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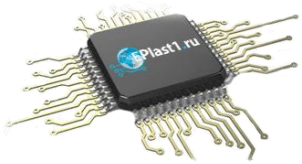
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)
Факс: 8 (812) 320-02-42
Электронная почта: org@eplast1.ru
Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.